US00D798831S

(12) **United States Design Patent** (10) **Patent No.: US D798,831 S**
Anzai et al. (45) **Date of Patent: ** *Oct. 3, 2017**

(54) **COOLING DEVICE FOR AN ELECTRONIC COMPONENT HEAT SINK**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

(21) Appl. No.: **29/566,047**

(22) Filed: **May 26, 2016**

(30) **Foreign Application Priority Data**

Dec. 4, 2015 (JP) 2015-027271

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179, 122, 182; D23/415, 330
CPC .. H05K 7/20; H05K 7/20172; H05K 7/20127; H05K 7/20336; H05K 7/20154; H05K 7/20272; H01L 23/34; H01L 23/3672; H01L 23/40; H01L 23/4006; H01L 23/4093; H01L 23/427; H01L 23/46; F28D 15/0275; F28D 1/0426; F28D 15/0208; F28D 15/04; F28D 15/02; F28F 1/30; F28F 2215/00; G06F 1/20
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a cooling device for an electronic component heat sink, as shown and described.

DESCRIPTION

FIG. **1** is a front, bottom, left-side perspective view of a cooling device for an electronic component heat sink showing our new design, the front, top, left-side being a mirror image thereof;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a right-side elevational view thereof;
FIG. **5** is a left-side elevational view thereof;
FIG. **6** is an enlarged view of an area shown in a dashed line box labeled "**6**" in FIG. **2**; and,
FIG. **7** is an enlarged view of an area shown in a dashed line box labeled "**7**" in FIG. **3**.
The dashed line boxes identify areas that are enlarged, and form no part of the claimed design.

1 Claim, 5 Drawing Sheets

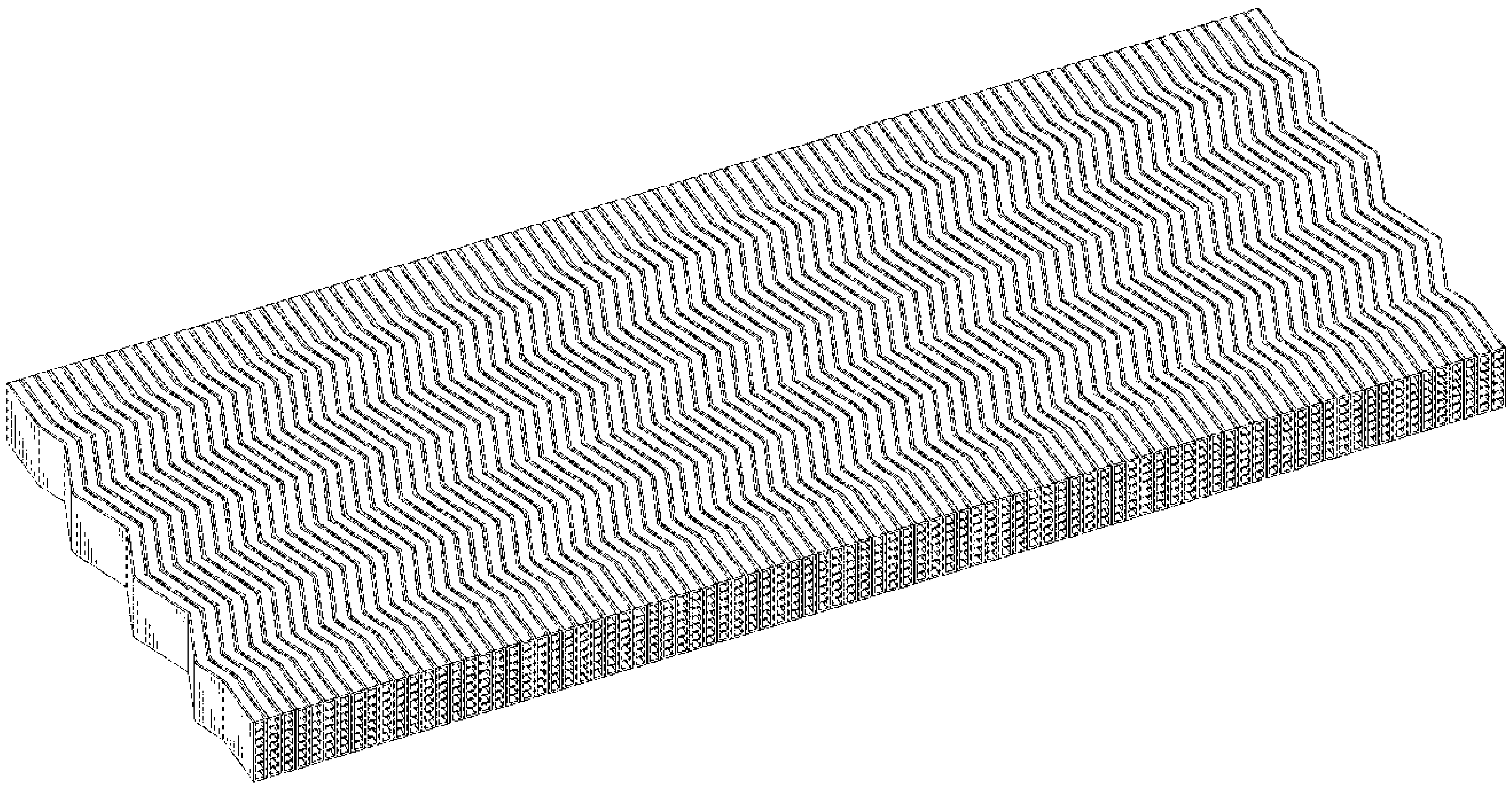

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FIG. 1

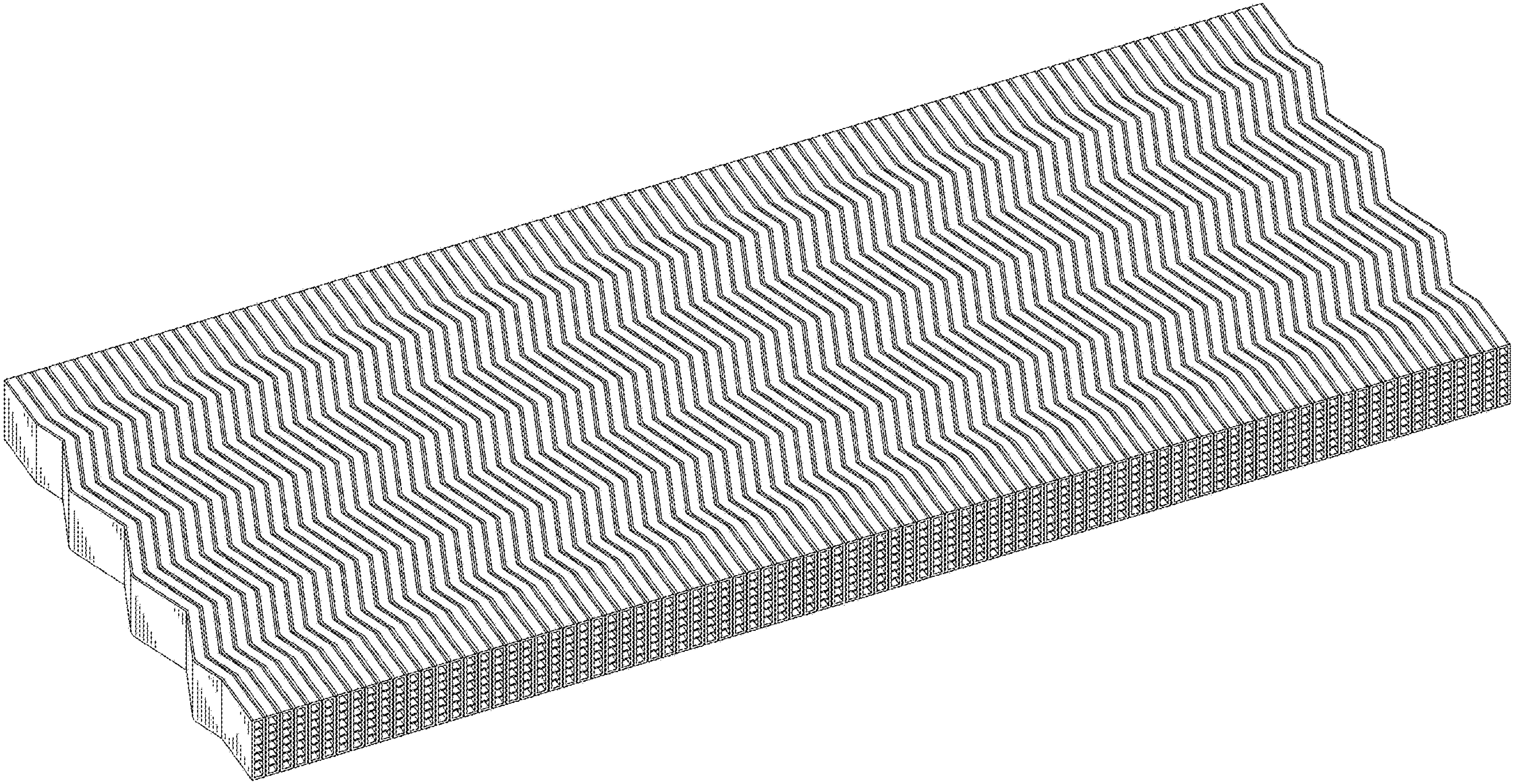


FIG. 2

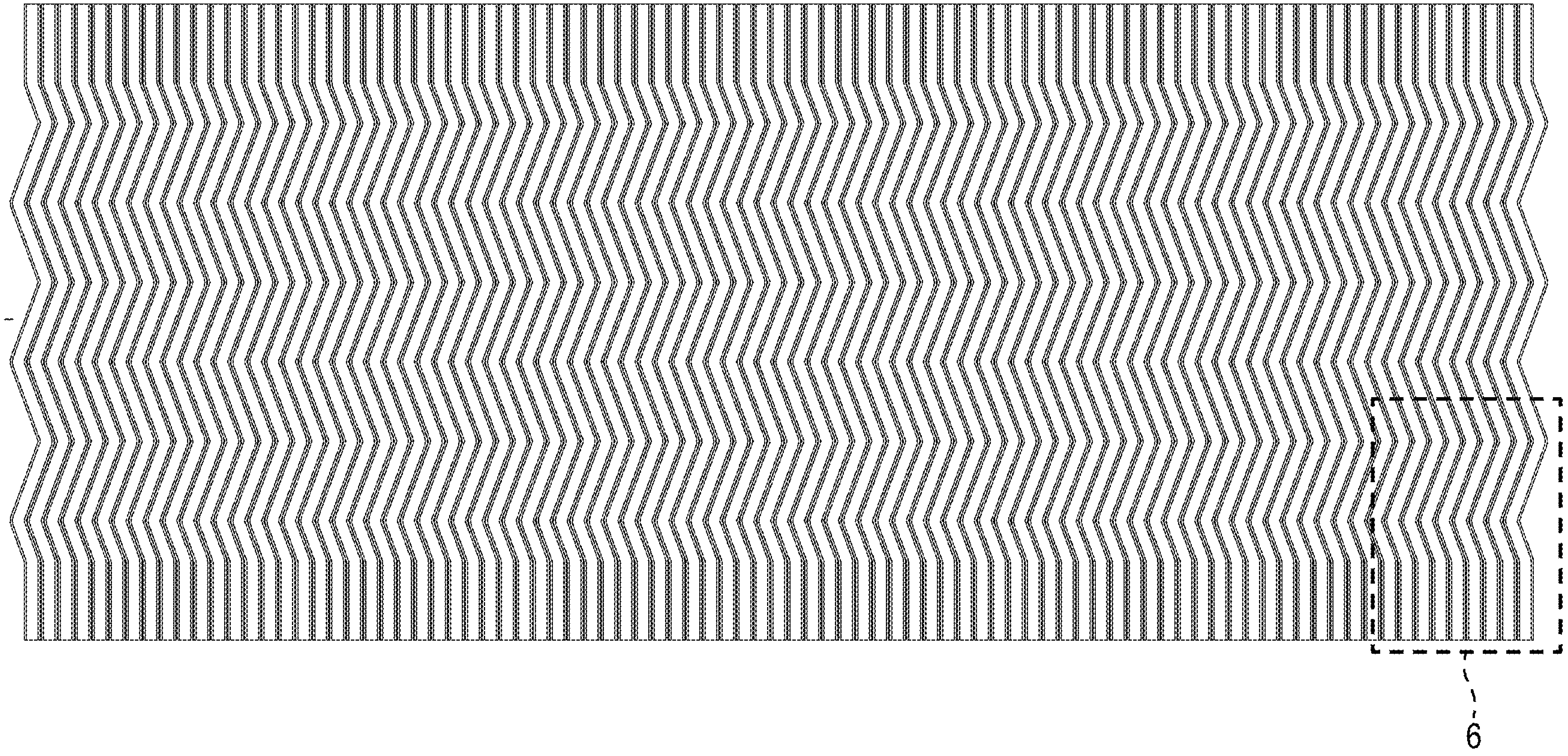


FIG. 3

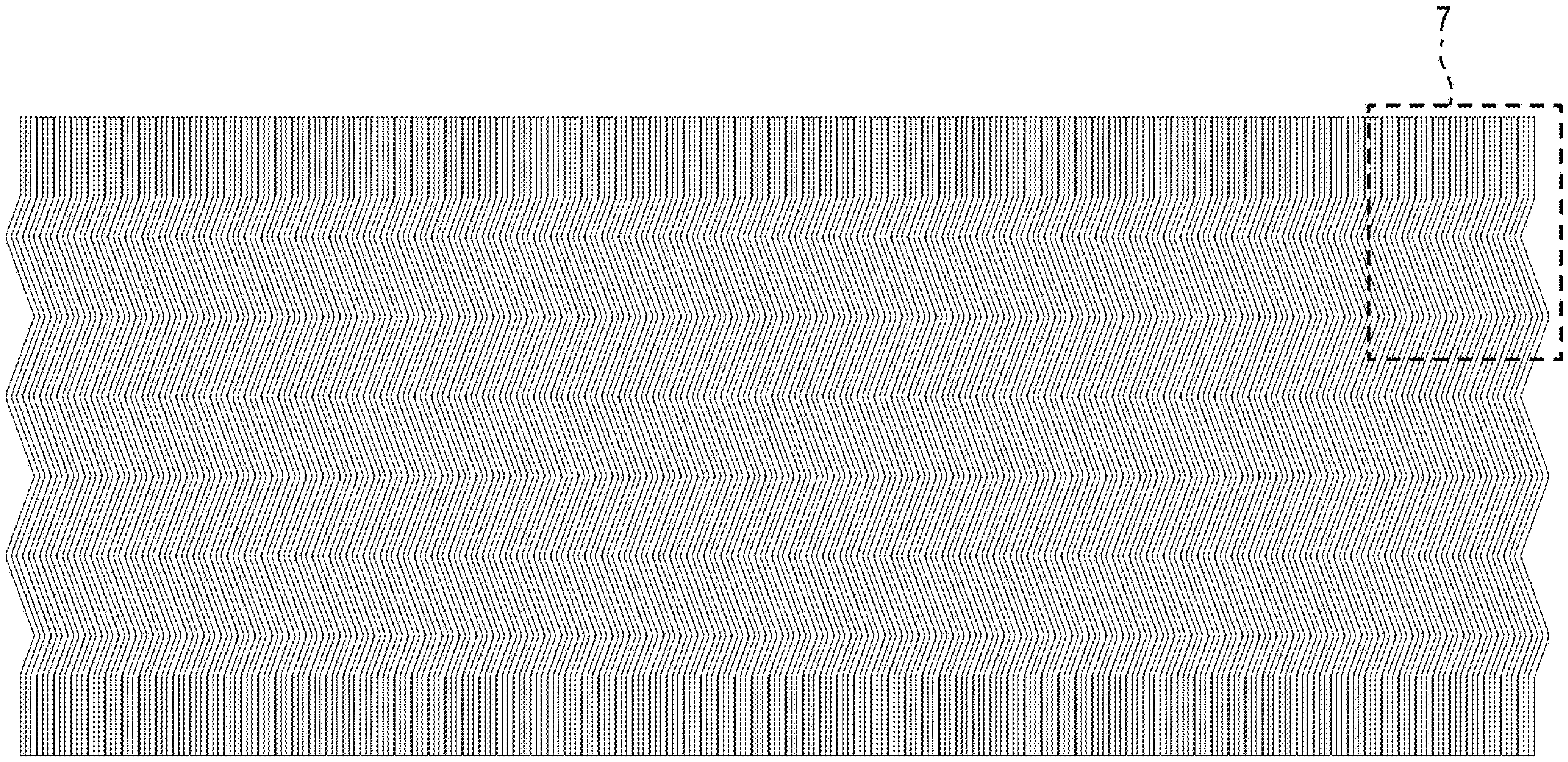


FIG. 4

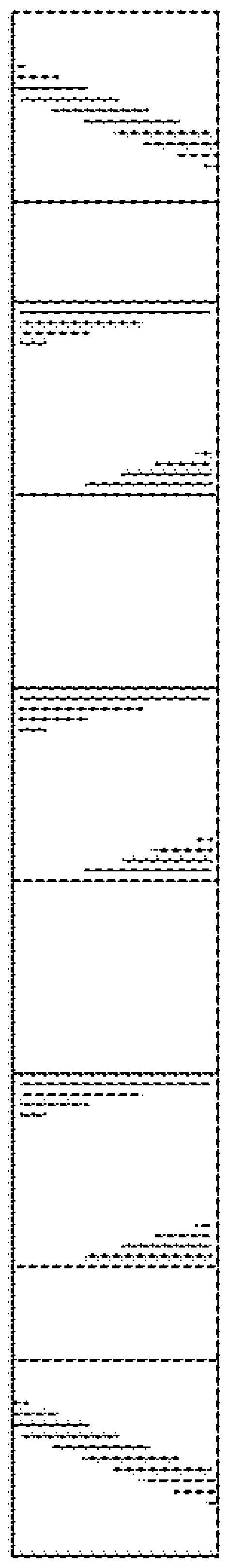
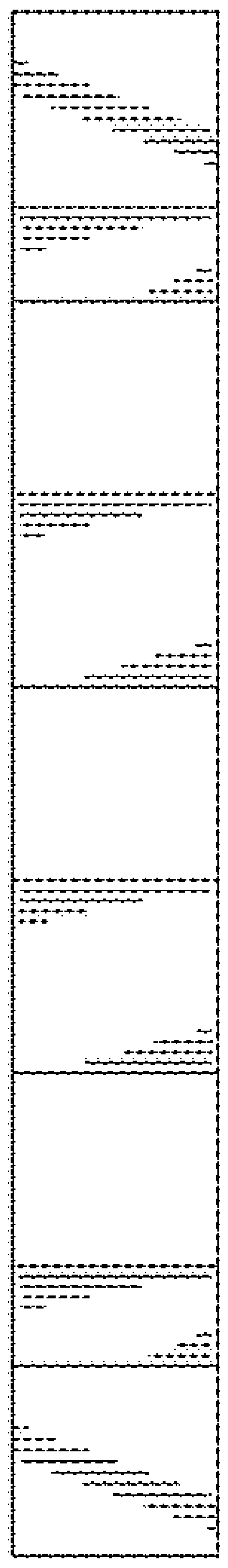


FIG. 5



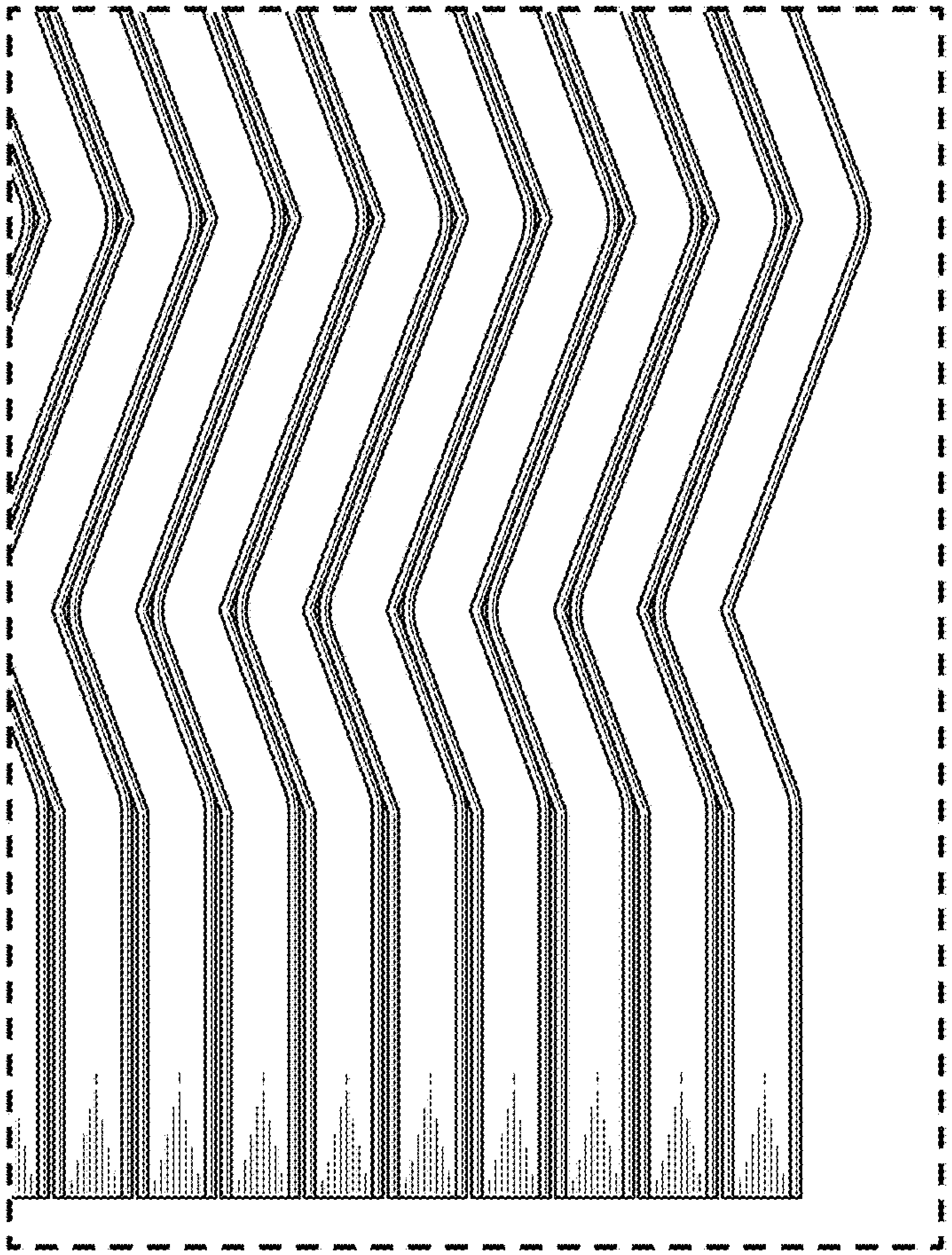


FIG. 6

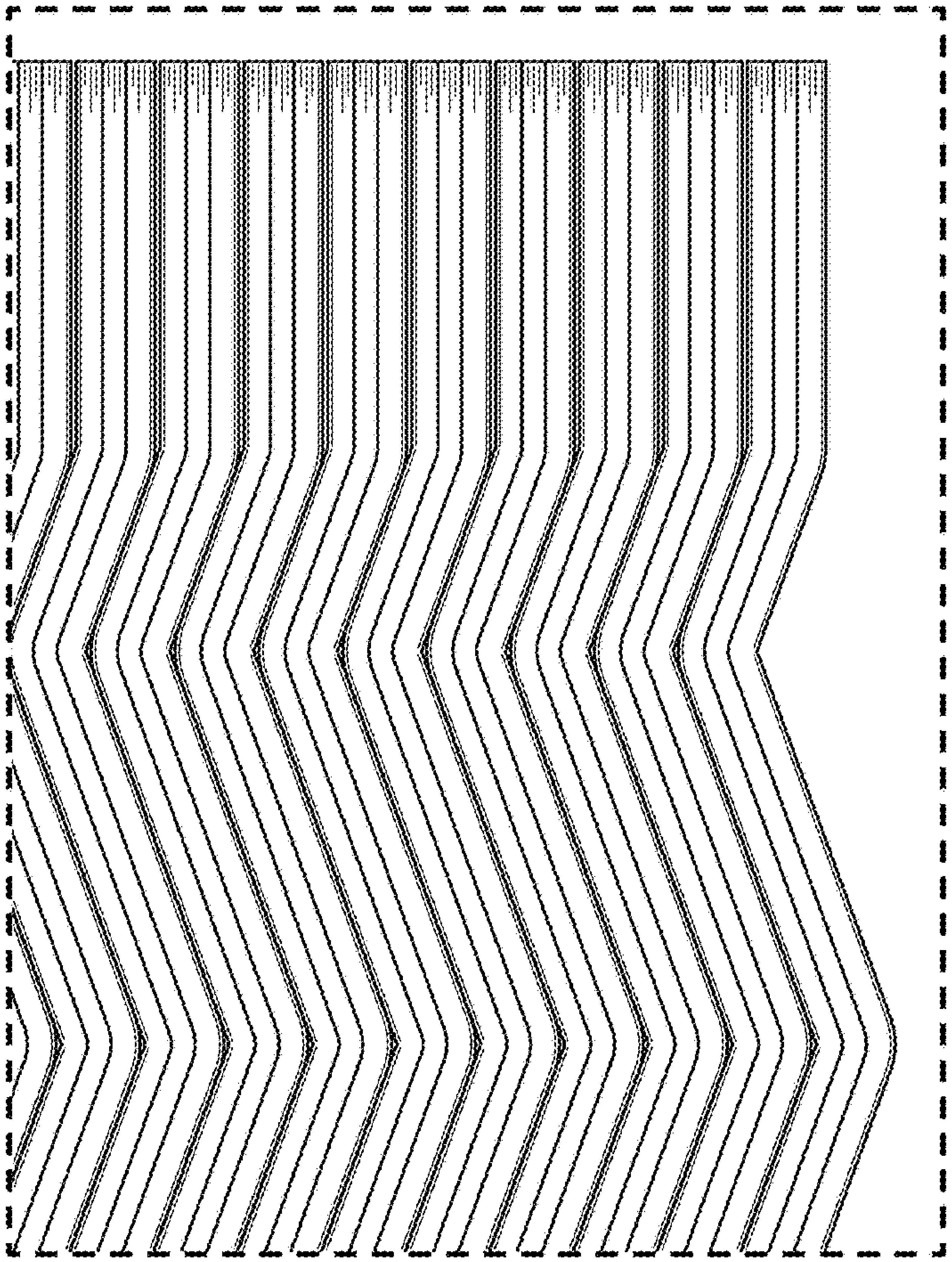


FIG. 7